



Vincotech

30-E312NIA400H702-PM40F28

datasheet

flowNPC E3BP

1200 V / 400 A

Topology features

- Kelvin Emitter for improved switching performance
- Temperature sensor
- Neutral Point Clamped Topology (I-Type)

Component features

- High speed switching
- Low collector emitter saturation voltage
- Low turn-off losses
- Optimized for hard switching topologies
- Positive temperature coefficient

Housing features

- Base isolation: Al_2O_3
- Cu baseplate
- Convex shaped baseplate for superior thermal contact
- CTI600 housing material
- Baseplate with rough surface
- Thermo-mechanical push-and-pull force relief
- Solder pin

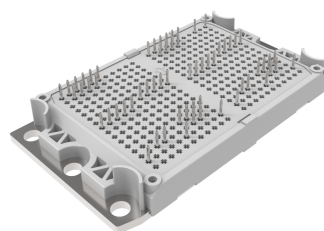
Target applications

- Energy Storage Systems
- Solar Inverters

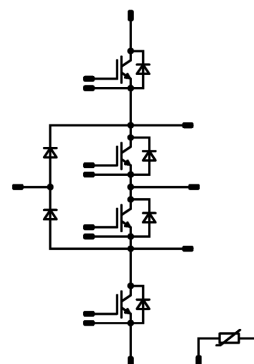
Types

- 30-E312NIA400H702-PM40F28

flow E3BP 12 mm housing



Schematic





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Maximum Ratings

$T_j = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
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Buck Switch

Collector-emitter voltage	V_{CES}		1200	V
Collector current (DC current)	I_C	$T_j = T_{jmax}$ $T_a = 80\text{ °C}$	316	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}	1200	A
Turn off safe operating area		$T_j = 150\text{ °C}$, $V_{CE} = 1200\text{ V}$	1200	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_a = 80\text{ °C}$	586	W
Gate-emitter voltage	V_{GES}		± 20	V
Maximum junction temperature	T_{jmax}		175	°C

Buck Diode

Peak repetitive reverse voltage	V_{RRM}		1200	V
Forward current (DC current)	I_F	$T_j = T_{jmax}$ $T_a = 80\text{ °C}$	159	A
Repetitive peak forward current	I_{FRM}	t_p limited by T_{jmax}	280	A
Surge (non-repetitive) forward current	I_{FSM}	Single Half Sine Wave, $t_p = 10\text{ ms}$ $T_j = 25\text{ °C}$	1120	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_a = 80\text{ °C}$	356	W
Maximum junction temperature	T_{jmax}		175	°C

Boost Switch

Collector-emitter voltage	V_{CES}		1200	V
Collector current (DC current)	I_C	$T_j = T_{jmax}$ $T_a = 80\text{ °C}$	316	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}	1200	A
Turn off safe operating area		$T_j = 150\text{ °C}$, $V_{CE} = 1200\text{ V}$	1200	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_a = 80\text{ °C}$	586	W
Gate-emitter voltage	V_{GES}		± 20	V
Maximum junction temperature	T_{jmax}		175	°C



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Maximum Ratings

$T_j = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Boost Diode				
Peak repetitive reverse voltage	V_{RRM}		1200	V
Forward current (DC current)	I_F	$T_j = T_{jmax}$ $T_a = 80\text{ °C}$	159	A
Repetitive peak forward current	I_{FRM}	t_p limited by T_{jmax}	280	A
Surge (non-repetitive) forward current	I_{FSM}	Single Half Sine Wave, $t_p = 10\text{ ms}$ $T_j = 25\text{ °C}$	1120	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_a = 80\text{ °C}$	356	W
Maximum junction temperature	T_{jmax}		175	°C

Boost Sw. Inv. Diode

Peak repetitive reverse voltage	V_{RRM}		1600	V
Forward current (DC current)	I_F	$T_j = T_{jmax}$ $T_a = 80\text{ °C}$	214	A
Surge (non-repetitive) forward current	I_{FSM}	Single Half Sine Wave, $t_p = 10\text{ ms}$ $T_j = 150\text{ °C}$	1620	A
Surge current capability	I^2t		13320	A ² s
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_a = 80\text{ °C}$	241	W
Maximum junction temperature	T_{jmax}		150	°C

Module Properties

Thermal Properties

Storage temperature	T_{stg}		-40...+125	°C
Operation temperature under switching condition	T_{jop}		-40...+($T_{jmax} - 25$)	°C

Isolation Properties

Isolation voltage	V_{isol}	DC Test Voltage* $t_p = 2\text{ s}$	6800	V
Creepage distance			12,67	mm
Clearance			> 12,7	mm
Comparative Tracking Index	CTI		≥ 600	

*100 % tested in production



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Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	

Buck Switch

Static

Gate-emitter threshold voltage	$V_{GE(th)}$	$V_{CE} = V_{GE}$			0,0064	25	4,7	5,5	6,2	V
Collector-emitter saturation voltage	$V_{CE(sat)}$		15		400	25 125 150		1,78 1,94 1,98	2,15 ⁽¹⁾	V
Collector-emitter cut-off current	I_{CES}		0	1200		25			16	µA
Gate-emitter leakage current	I_{GES}		20	0		25			400	nA
Internal gate resistance	r_g							None		Ω
Input capacitance	C_{ies}	$f = 100 \text{ kHz}$	0	25		25		52000		pF
Output capacitance	C_{oes}							960		pF
Reverse transfer capacitance	C_{res}							288		pF
Gate charge	Q_g	$V_{CC} = 960 \text{ V}$	0/15		400	25		2856		nC

Thermal

Thermal resistance junction to sink ⁽²⁾	$R_{th(j-s)}$	$\lambda_{paste} = 5,2 \text{ W/mK}$ (PTM)						0,16		K/W
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Dynamic

Turn-on delay time	$t_{d(on)}$	$R_{gon} = 4 \text{ } \Omega$ $R_{goff} = 4 \text{ } \Omega$	± 15	600	280	25 125 150		331,19 330,64 331,06		ns
Rise time	t_r					25 125 150		30,3 30,62 30,89		ns
Turn-off delay time	$t_{d(off)}$					25 125 150		287,66 326,08 336,33		ns
Fall time	t_f					25 125 150		32,89 67,85 82,25		ns
Turn-on energy (per pulse)	E_{on}	$Q_{tFWD}=0,534 \text{ } \mu\text{C}$ $Q_{tFWD}=0,552 \text{ } \mu\text{C}$ $Q_{tFWD}=0,541 \text{ } \mu\text{C}$				25 125 150		8,82 8,85 8,95		mWs
Turn-off energy (per pulse)	E_{off}					25 125 150		7,75 12,95 14,68		mWs



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Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	

Buck Diode

Static

Forward voltage	V_F				140	25 125 150		1,52 1,87 2,01	1,6 ⁽¹⁾ 2,3 ⁽¹⁾	V
Reverse leakage current	I_R	$V_r = 1200$ V				25 150		14 70	420 2100	µA

Thermal

Thermal resistance junction to sink ⁽²⁾	$R_{th(j-s)}$	$\lambda_{paste} = 5,2$ W/mK (PTM)						0,27		K/W
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Dynamic

Peak recovery current	I_{RM}	$di/dt=4613$ A/µs $di/dt=11736$ A/µs $di/dt=7665$ A/µs	± 15	600	280	25 125 150		49,12 53,82 54,71		A
Reverse recovery time	t_{rr}					25 125 150		20,69 21,74 21,23		ns
Recovered charge	Q_r					25 125 150		0,534 0,552 0,541		µC
Reverse recovered energy	E_{rec}					25 125 150		0,082 0,081 0,08		mWs
Peak rate of fall of recovery current	$(di_{rr}/dt)_{max}$					25 125 150		4583,69 7793,55 7396,29		A/µs



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Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
		V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]		Min	Typ	Max	

Boost Switch

Static

Gate-emitter threshold voltage	$V_{GE(th)}$	$V_{CE} = V_{GE}$			0,0064	25	4,7	5,5	6,2	V
Collector-emitter saturation voltage	V_{CEsat}		15		400	25 125 150		1,78 1,94 1,98	2,15 ⁽¹⁾	V
Collector-emitter cut-off current	I_{CES}		0	1200		25			16	µA
Gate-emitter leakage current	I_{GES}		20	0		25			400	nA
Internal gate resistance	r_g							None		Ω
Input capacitance	C_{ies}	$f = 100 \text{ kHz}$	0	25	25			52000		pF
Output capacitance	C_{oes}							960		pF
Reverse transfer capacitance	C_{res}							288		pF
Gate charge	Q_g	$V_{CC} = 960 \text{ V}$	0/15		400	25		2856		nC

Thermal

Thermal resistance junction to sink ⁽²⁾	$R_{th(j-s)}$	$\lambda_{paste} = 5,2 \text{ W/mK}$ (PTM)						0,16		K/W
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Dynamic

Turn-on delay time	$t_{d(on)}$	$R_{gon} = 4 \text{ Ω}$ $R_{goff} = 4 \text{ Ω}$	±15	600	280	25 125 150		334,28 333,46 334,17		ns
Rise time	t_r					25 125 150		20,83 22,43 23,09		ns
Turn-off delay time	$t_{d(off)}$					25 125 150		292,44 331,47 342,54		ns
Fall time	t_f					25 125 150		30,82 84,85 101,72		ns
Turn-on energy (per pulse)	E_{on}					25 125 150		9,45 10,15 12,35		mWs
Turn-off energy (per pulse)	E_{off}					25 125 150		8,64 14,78 18,05		mWs



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Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	

Boost Diode

Static

Forward voltage	V_F				140	25 125 150		1,52 1,87 2,01	1,6 ⁽¹⁾ 2,3 ⁽¹⁾	V
Reverse leakage current	I_R	$V_r = 1200$ V				25 150		14 70	420 2100	µA

Thermal

Thermal resistance junction to sink ⁽²⁾	$R_{th(j-s)}$	$\lambda_{paste} = 5,2$ W/mK (PTM)						0,27		K/W
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Dynamic

Peak recovery current	I_{RM}	$di/dt=11167$ A/µs $di/dt=12577$ A/µs $di/dt=16040$ A/µs	± 15	600	280	25 125 150		109,77 114,44 116,46		A
Reverse recovery time	t_{rr}					25 125 150		20,09 20,22 20,21		ns
Recovered charge	Q_r					25 125 150		1,34 1,41 1,41		µC
Reverse recovered energy	E_{rec}					25 125 150		0,367 0,397 0,399		mWs
Peak rate of fall of recovery current	$(di_{rr}/dt)_{max}$					25 125 150		13469,99 14904,26 13747,91		A/µs



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Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	

Boost Sw. Inv. Diode

Static

Forward voltage	V_F				168	25 125		1,12 1,07	1,5 ⁽¹⁾	V
Reverse leakage current	I_R	$V_r = 1600$ V				25 150			600 6000	µA

Thermal

Thermal resistance junction to sink ⁽²⁾	$R_{th(j-s)}$	$\lambda_{paste} = 5,2$ W/mK (PTM)						0,29		K/W
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Thermistor

Static

Rated resistance	R					25		22		kΩ
Deviation of R100	$\Delta_{R/R}$	$R_{100} = 1484$ Ω				100	-5		5	%
Power dissipation	P					25		130		mW
Power dissipation constant	d					25		1,5		mW/K
B-value	$B_{(25/50)}$	Tol. ±1 %						3962		K
B-value	$B_{(25/100)}$	Tol. ±1 %						4000		K
Vincotech Thermistor Reference									I	

⁽¹⁾ Value at chip level

⁽²⁾ Only valid with pre-applied Vincotech thermal interface material.



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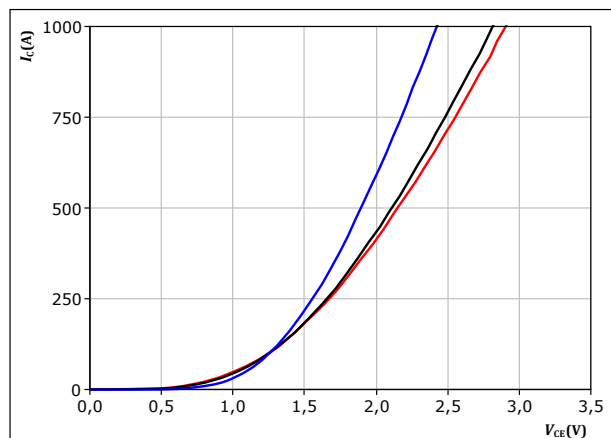
datasheet

Buck Switch Characteristics

figure 1. IGBT

Typical output characteristics

$$I_C = f(V_{CE})$$

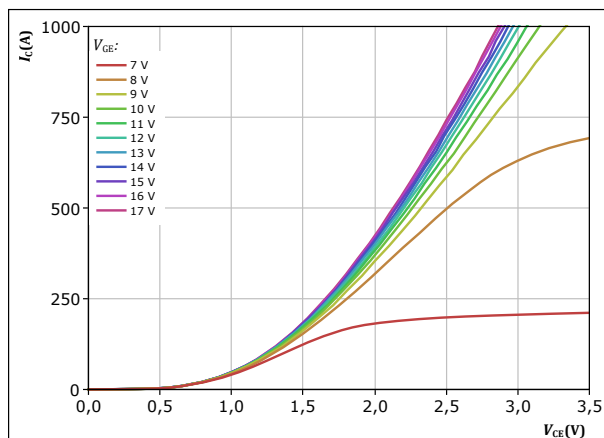


$t_p = 250 \mu s$
 $V_{GE} = 15 V$
 $T_j:$ 25 °C, 125 °C, 150 °C

figure 2. IGBT

Typical output characteristics

$$I_C = f(V_{CE})$$

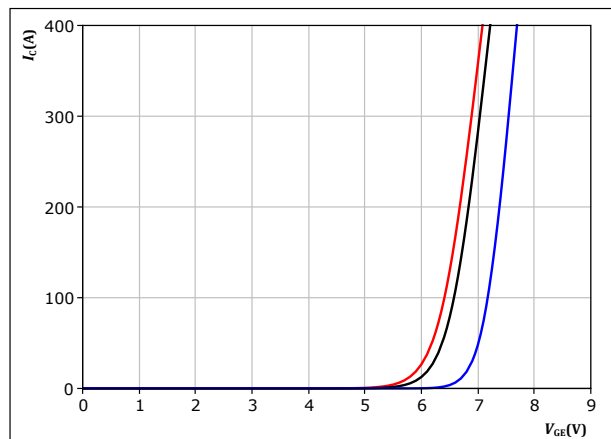


$t_p = 250 \mu s$
 $T_j = 150 \text{ } ^\circ C$
 V_{GE} from 7 V to 17 V in steps of 1 V

figure 3. IGBT

Typical transfer characteristics

$$I_C = f(V_{GE})$$

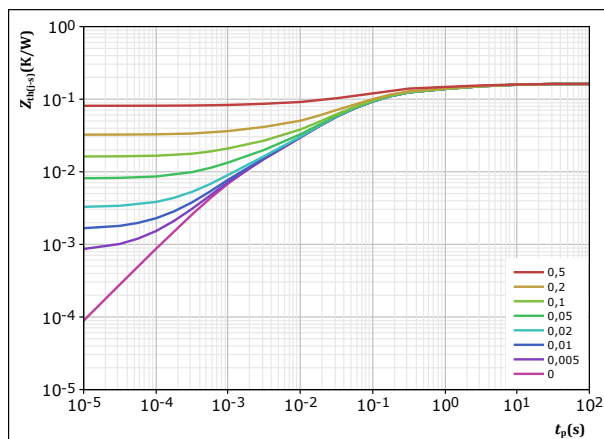


$t_p = 250 \mu s$
 $V_{CE} = 48 V$
 $T_j:$ 25 °C, 125 °C, 150 °C

figure 4. IGBT

Transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



$D = t_p / T$
 $R_{th(j-s)} = 0.162 K/W$
IGBT thermal model values

$R (K/W)$	$\tau (s)$
1,67E-02	6,66E+00
2,58E-02	1,01E+00
7,90E-02	1,01E-01
3,31E-02	1,76E-02
7,60E-03	1,22E-03



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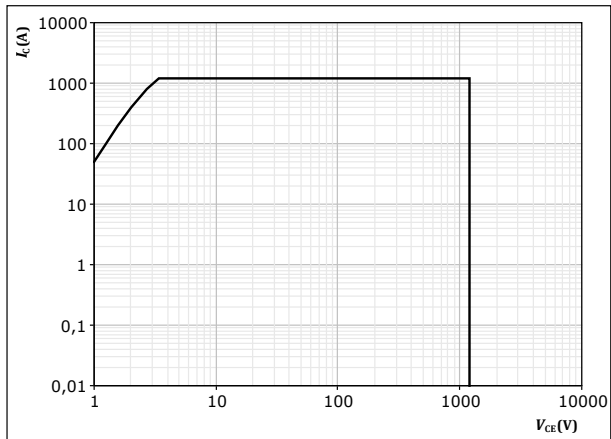
datasheet

Buck Switch Characteristics

figure 5. IGBT

Safe operating area

$$I_C = f(V_{CE})$$

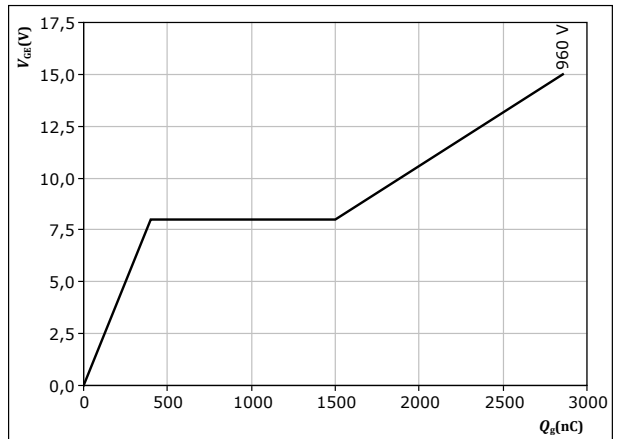


$D =$ single pulse
 $T_s = 80$ °C
 $V_{GE} = 15$ V
 $T_j = T_{jmax}$

figure 6. IGBT

Gate voltage vs gate charge

$$V_{GE} = f(Q_g)$$



$I_C = 400$ A
 $T_j = 25$ °C



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Buck Diode Characteristics

figure 7. FWD

Typical forward characteristics

$$I_F = f(V_F)$$

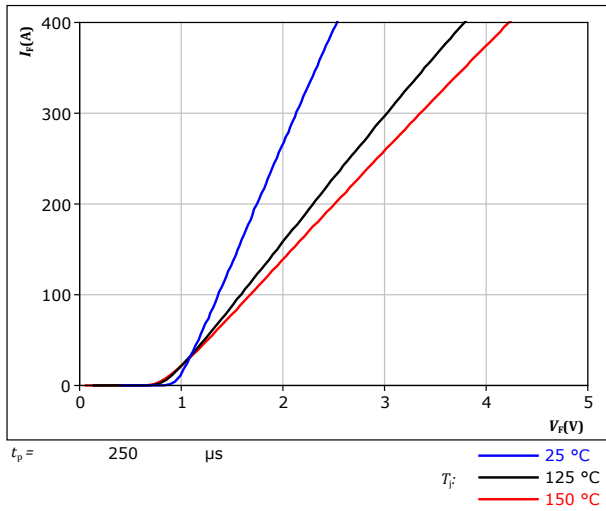
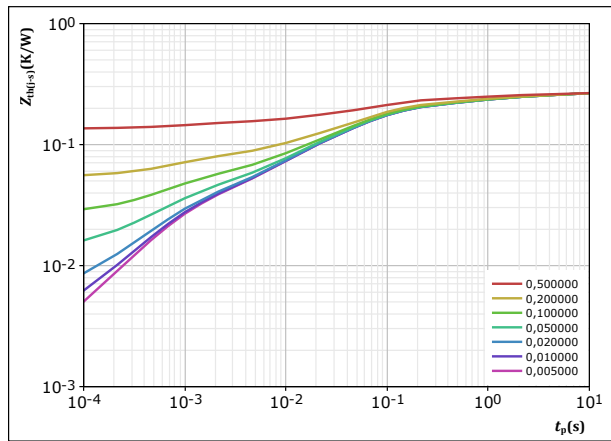


figure 8. FWD

Transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$





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Boost Switch Characteristics

figure 9. IGBT

Typical output characteristics

$$I_C = f(V_{CE})$$

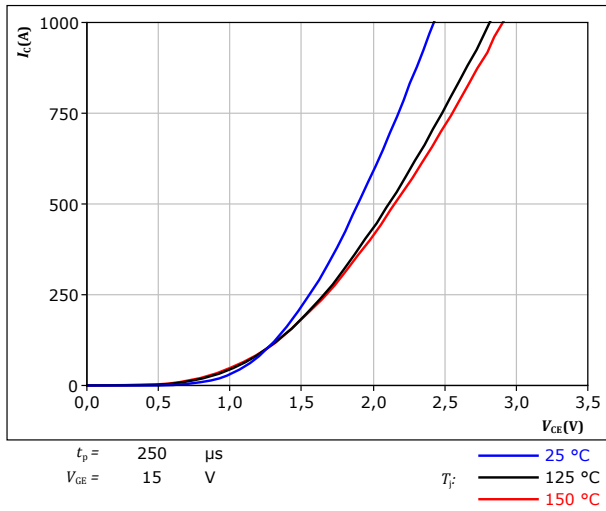


figure 10. IGBT

Typical output characteristics

$$I_C = f(V_{CE})$$

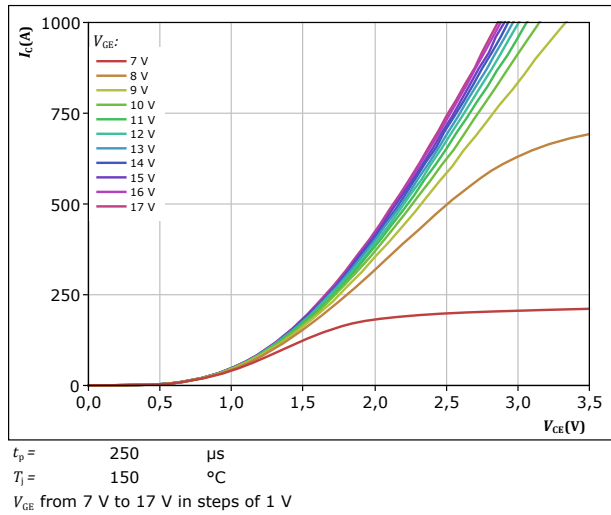


figure 11. IGBT

Typical transfer characteristics

$$I_C = f(V_{GE})$$

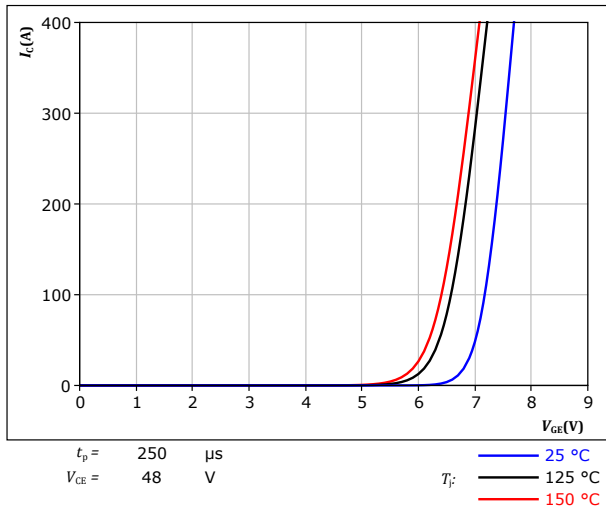
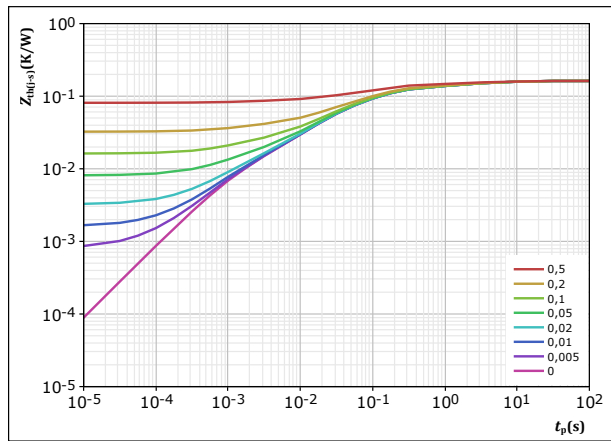


figure 12. IGBT

Transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$





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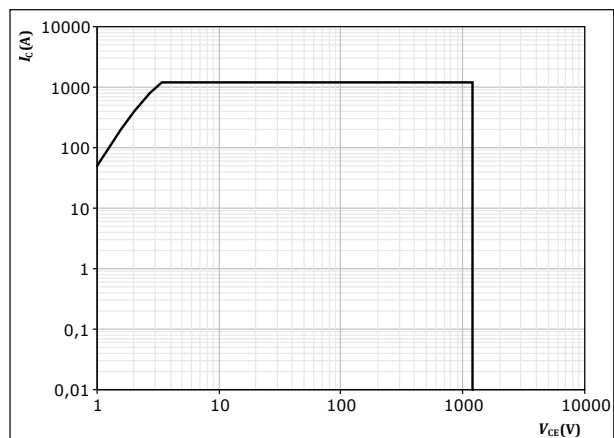
Boost Switch Characteristics

figure 13.

IGBT

Safe operating area

$$I_C = f(V_{CE})$$



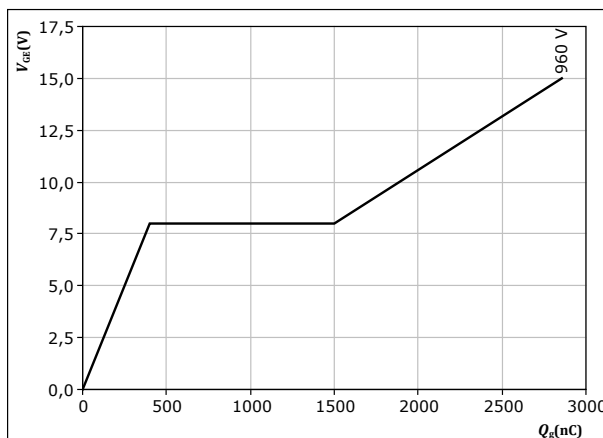
$D =$ single pulse
 $T_s = 80$ °C
 $V_{GE} = 15$ V
 $T_j = T_{jmax}$

figure 14.

IGBT

Gate voltage vs gate charge

$$V_{GE} = f(Q_g)$$



$I_C = 400$ A
 $T_j = 25$ °C



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Boost Diode Characteristics

figure 15.

FWD

Typical forward characteristics

$$I_F = f(V_F)$$

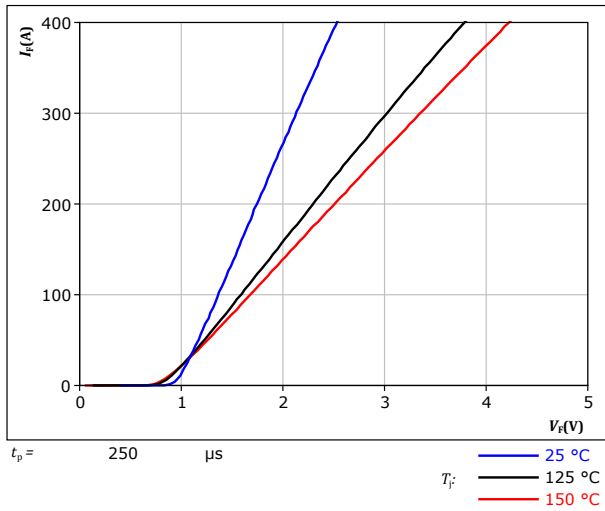
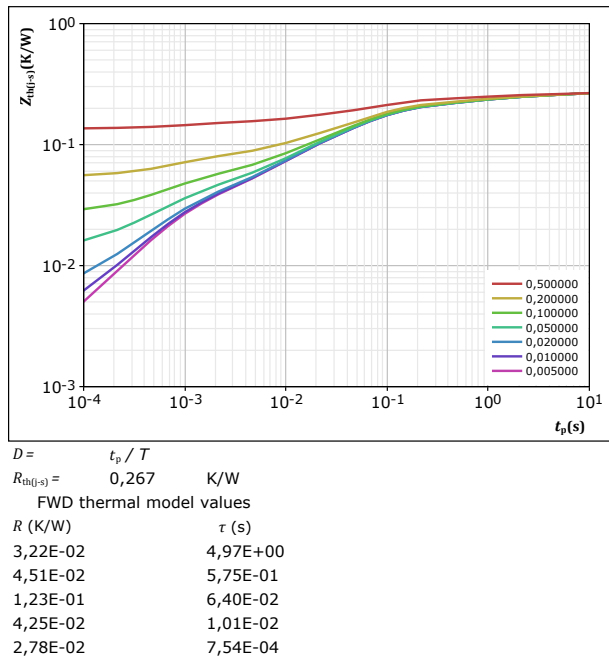


figure 16.

FWD

Transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$





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Boost Sw. Inv. Diode Characteristics

figure 17.

Rectifier

Typical forward characteristics

$$I_F = f(V_F)$$

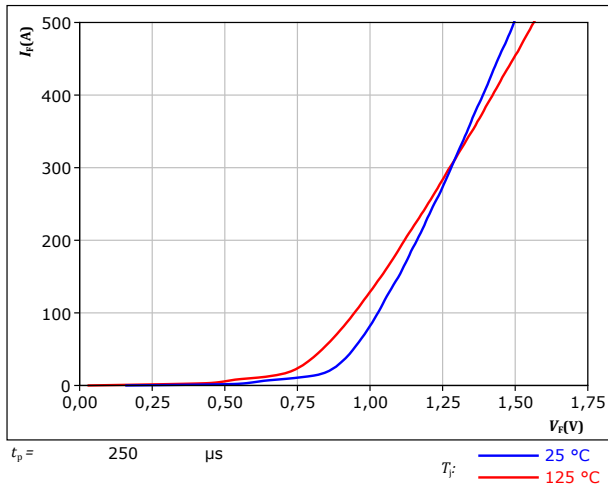
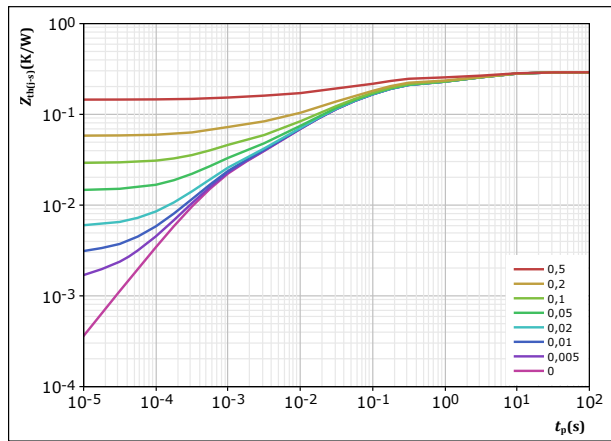


figure 18.

Rectifier

Transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



$D =$	t_p / T	
$R_{th(j-s)} =$	0,291	K/W
Rectifier thermal model values		
R (K/W)	τ (s)	
2,45E-02	8,61E+00	
5,77E-02	2,62E+00	
1,25E-01	9,71E-02	
6,19E-02	1,18E-02	
2,11E-02	7,09E-04	



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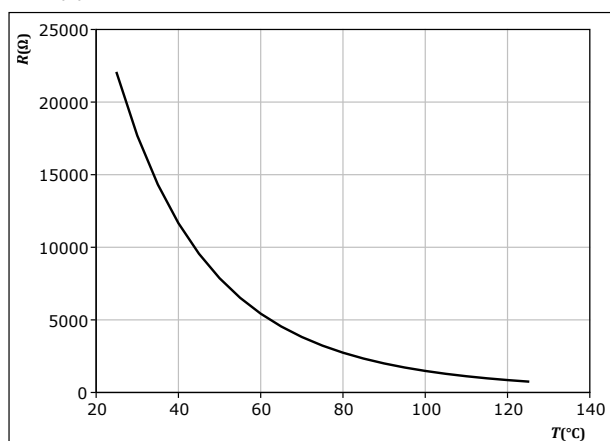
Thermistor Characteristics

figure 19.

Thermistor

Typical NTC characteristic as function of temperature

$$R_T = f(T)$$





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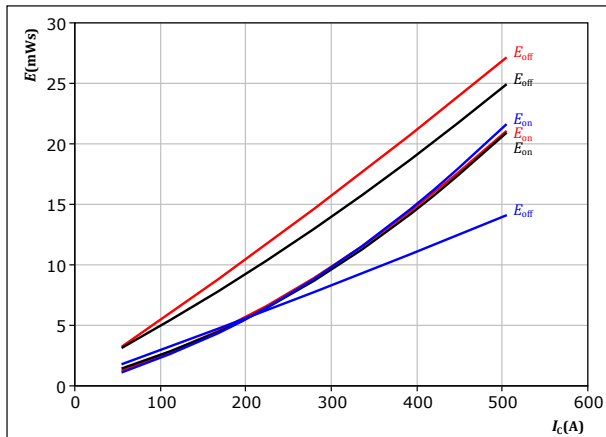
Buck Switching Characteristics

figure 20.

IGBT

Typical switching energy losses as a function of collector current

$$E = f(I_C)$$



With an inductive load at

$V_{CE} = 600 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $R_{gon} = 4 \text{ } \Omega$
 $R_{goff} = 4 \text{ } \Omega$

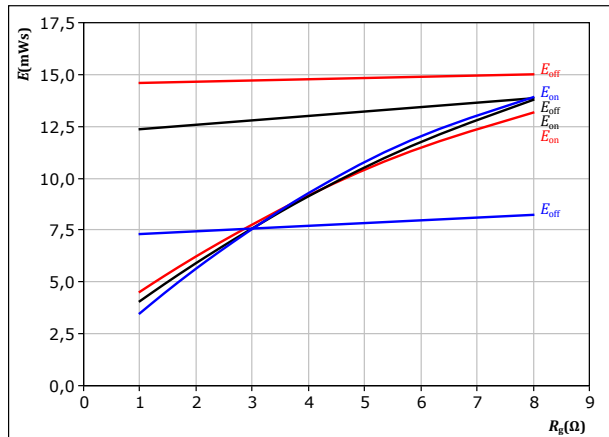
T_j :
— 25 °C
— 125 °C
— 150 °C

figure 21.

IGBT

Typical switching energy losses as a function of IGBT turn on gate resistor

$$E = f(R_g)$$



With an inductive load at

$V_{CE} = 600 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $I_C = 280 \text{ A}$

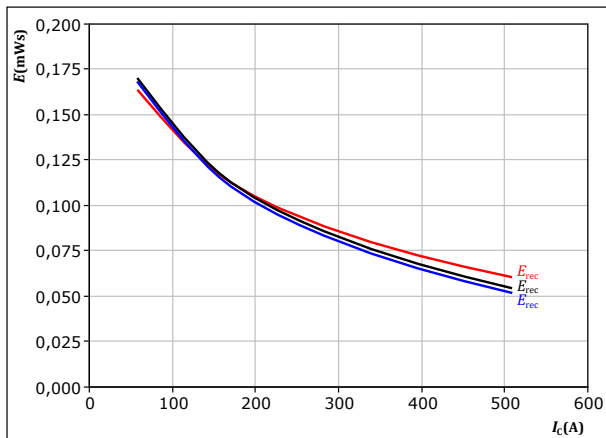
T_j :
— 25 °C
— 125 °C
— 150 °C

figure 22.

FWD

Typical reverse recovered energy loss as a function of collector current

$$E_{rec} = f(I_C)$$



With an inductive load at

$V_{CE} = 600 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $R_{gon} = 4 \text{ } \Omega$

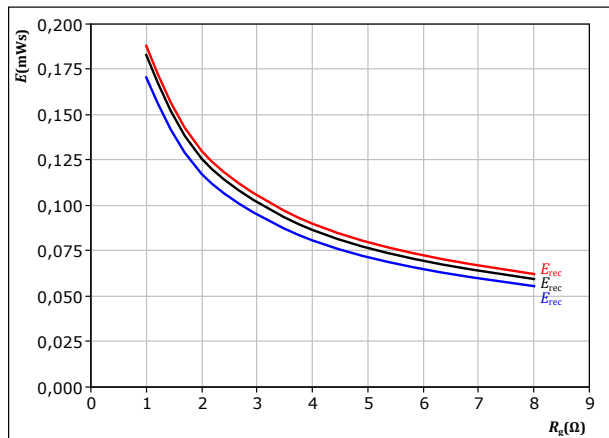
T_j :
— 25 °C
— 125 °C
— 150 °C

figure 23.

FWD

Typical reverse recovered energy loss as a function of IGBT turn on gate resistor

$$E_{rec} = f(R_g)$$



With an inductive load at

$V_{CE} = 600 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $I_C = 280 \text{ A}$

T_j :
— 25 °C
— 125 °C
— 150 °C



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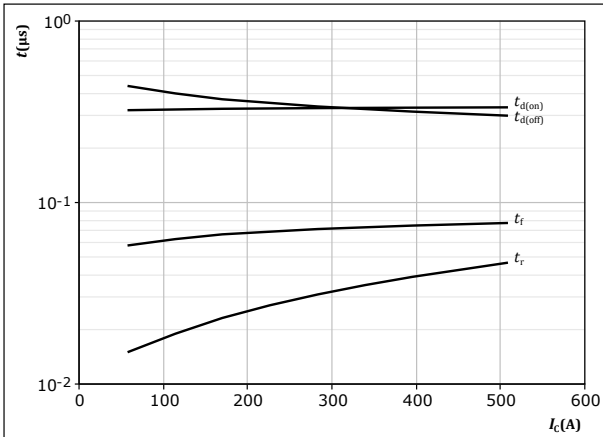
datasheet

Buck Switching Characteristics

figure 24.

IGBT

Typical switching times as a function of collector current
 $t = f(I_C)$



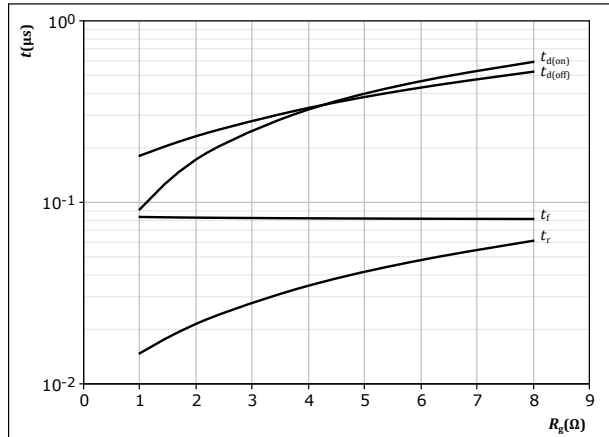
With an inductive load at

$T_j = 150$ °C
 $V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $R_{gon} = 4$ Ω
 $R_{goff} = 4$ Ω

figure 25.

IGBT

Typical switching times as a function of IGBT turn on gate resistor
 $t = f(R_g)$



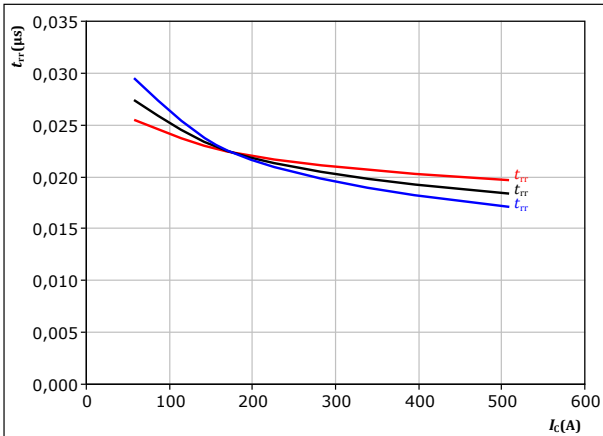
With an inductive load at

$T_j = 150$ °C
 $V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $I_C = 280$ A

figure 26.

FWD

Typical reverse recovery time as a function of collector current
 $t_{rr} = f(I_C)$



With an inductive load at

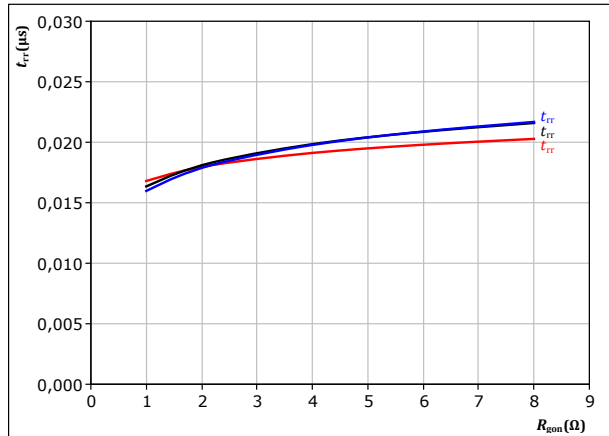
$V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $R_{gon} = 4$ Ω

T_j : 25 °C
125 °C
150 °C

figure 27.

FWD

Typical reverse recovery time as a function of IGBT turn on gate resistor
 $t_{rr} = f(R_{gon})$



With an inductive load at

$V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $I_C = 280$ A

T_j : 25 °C
125 °C
150 °C



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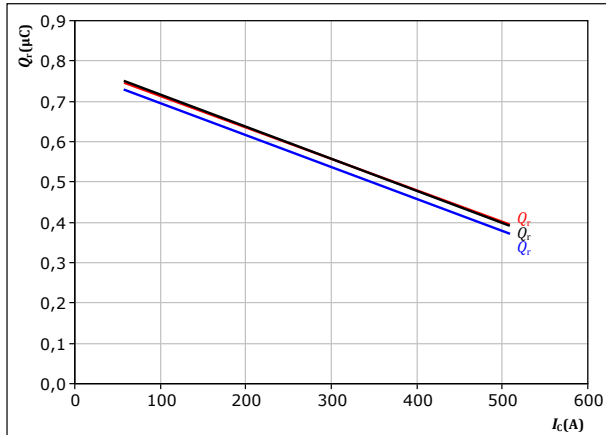
datasheet

Buck Switching Characteristics

figure 28. FWD

Typical recovered charge as a function of collector current

$$Q_r = f(I_c)$$



With an inductive load at

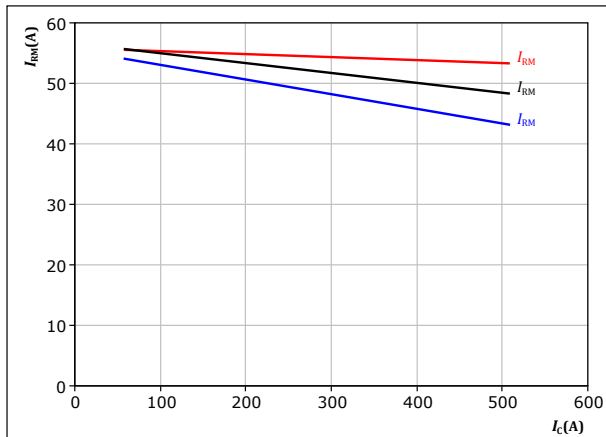
$V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $R_{gon} = 4$ Ω

T_j :
— 25 °C
— 125 °C
— 150 °C

figure 30. FWD

Typical peak reverse recovery current as a function of collector current

$$I_{RM} = f(I_c)$$



With an inductive load at

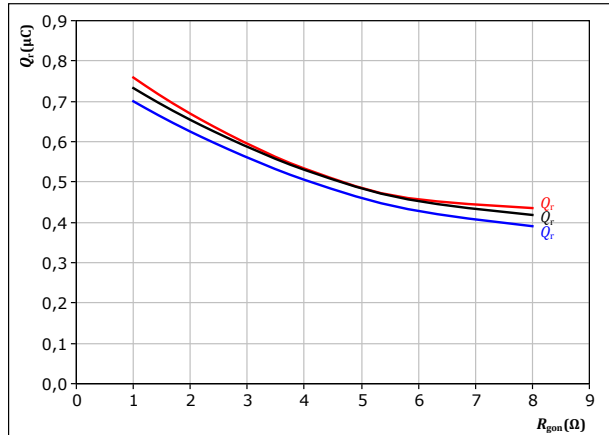
$V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $R_{gon} = 4$ Ω

T_j :
— 25 °C
— 125 °C
— 150 °C

figure 29. FWD

Typical recovered charge as a function of IGBT turn on gate resistor

$$Q_r = f(R_{gon})$$



With an inductive load at

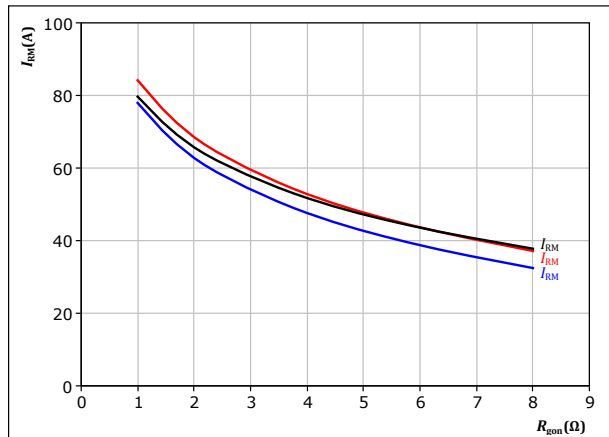
$V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $I_c = 280$ A

T_j :
— 25 °C
— 125 °C
— 150 °C

figure 31. FWD

Typical peak reverse recovery current as a function of IGBT turn on gate resistor

$$I_{RM} = f(R_{gon})$$



With an inductive load at

$V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $I_c = 280$ A

T_j :
— 25 °C
— 125 °C
— 150 °C

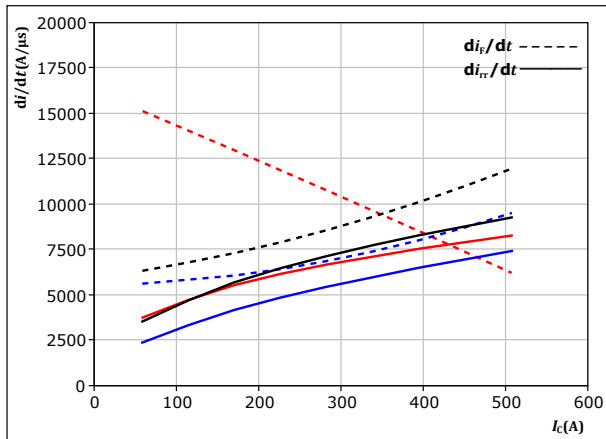


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Buck Switching Characteristics

figure 32. FWD

Typical rate of fall of forward and reverse recovery current as a function of collector current
 $di_f/dt, di_r/dt = f(I_C)$

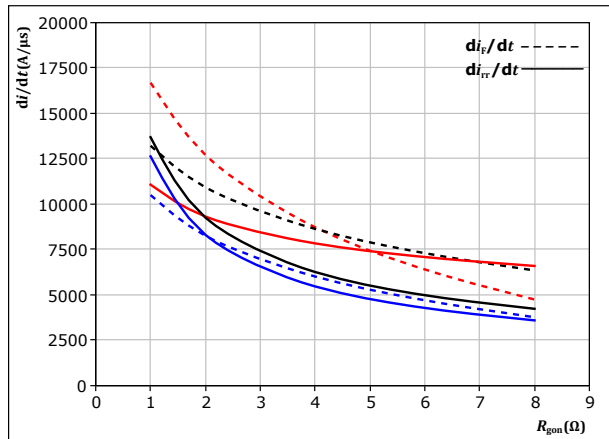


With an inductive load at

$V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $R_{gon} = 4$ Ω
 $T_j: 25$ °C
 125 °C
 150 °C

figure 33. FWD

Typical rate of fall of forward and reverse recovery current as a function of turn on gate resistor
 $di_f/dt, di_r/dt = f(R_{gon})$



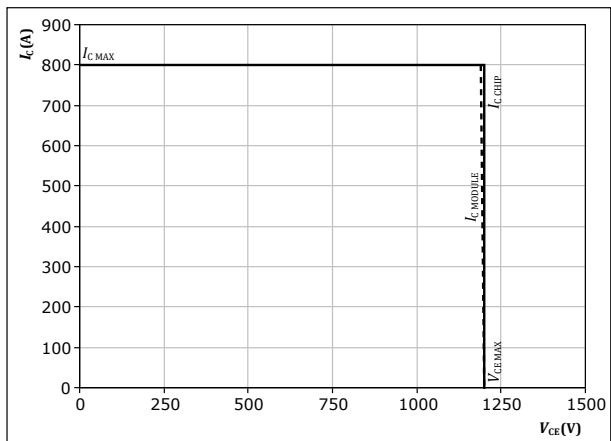
With an inductive load at

$V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $I_C = 280$ A
 $T_j: 25$ °C
 125 °C
 150 °C

figure 34. IGBT

Reverse bias safe operating area

$I_C = f(V_{CE})$



At $T_j = 150$ °C
 $R_{gon} = 4$ Ω
 $R_{goff} = 4$ Ω



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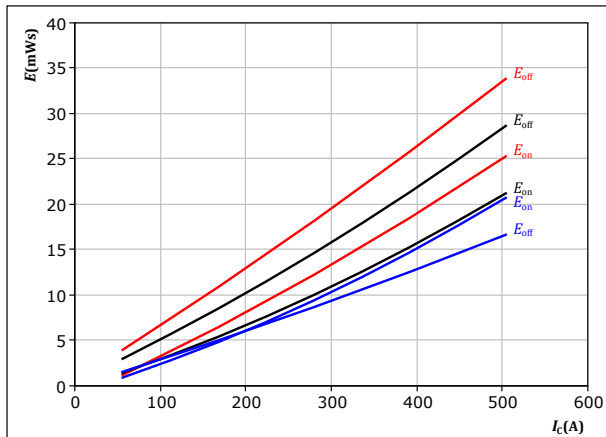
30-E312NIA400H702-PM40F28

datasheet

Boost Switching Characteristics

figure 35. IGBT

Typical switching energy losses as a function of collector current
 $E = f(I_C)$



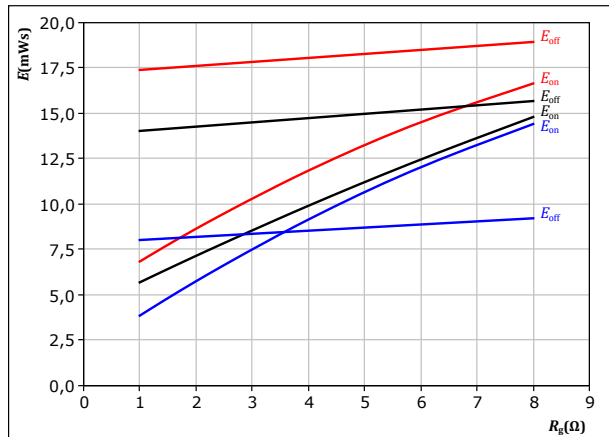
With an inductive load at

$V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $R_{gon} = 4$ Ω
 $R_{goff} = 4$ Ω

T_j : 25 °C (blue), 125 °C (black), 150 °C (red)

figure 36. IGBT

Typical switching energy losses as a function of IGBT turn on gate resistor
 $E = f(R_g)$



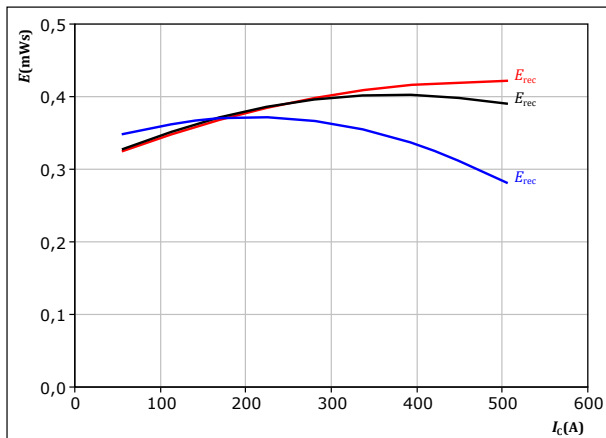
With an inductive load at

$V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $I_C = 280$ A

T_j : 25 °C (blue), 125 °C (black), 150 °C (red)

figure 37. FWD

Typical reverse recovered energy loss as a function of collector current
 $E_{rec} = f(I_C)$



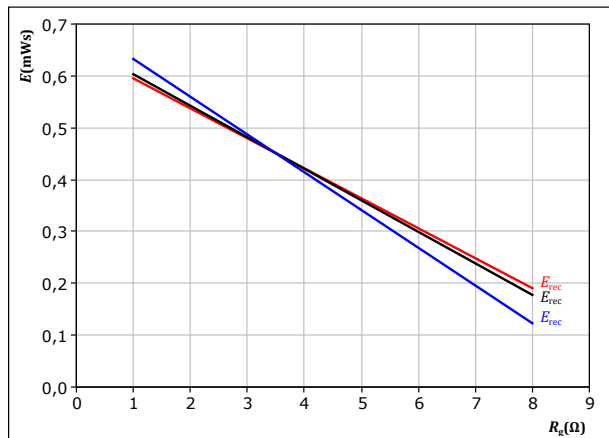
With an inductive load at

$V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $R_{gon} = 4$ Ω

T_j : 25 °C (blue), 125 °C (black), 150 °C (red)

figure 38. FWD

Typical reverse recovered energy loss as a function of IGBT turn on gate resistor
 $E_{rec} = f(R_g)$



With an inductive load at

$V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $I_C = 280$ A

T_j : 25 °C (blue), 125 °C (black), 150 °C (red)



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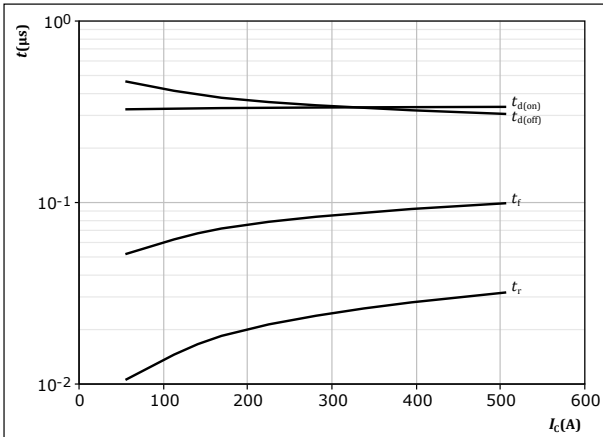
datasheet

Boost Switching Characteristics

figure 39.

IGBT

Typical switching times as a function of collector current
 $t = f(I_c)$



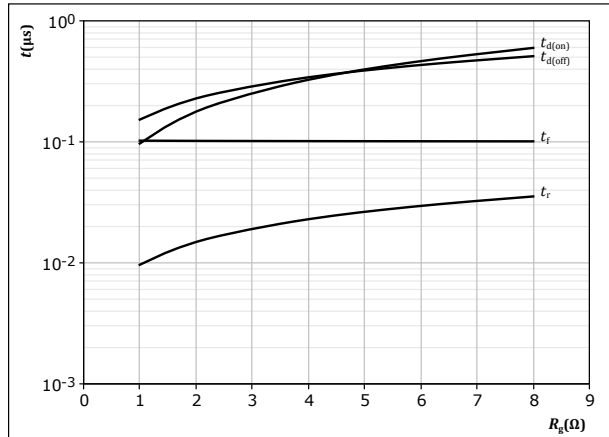
With an inductive load at

$T_j = 150$ °C
 $V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $R_{gon} = 4$ Ω
 $R_{goff} = 4$ Ω

figure 40.

IGBT

Typical switching times as a function of IGBT turn on gate resistor
 $t = f(R_g)$



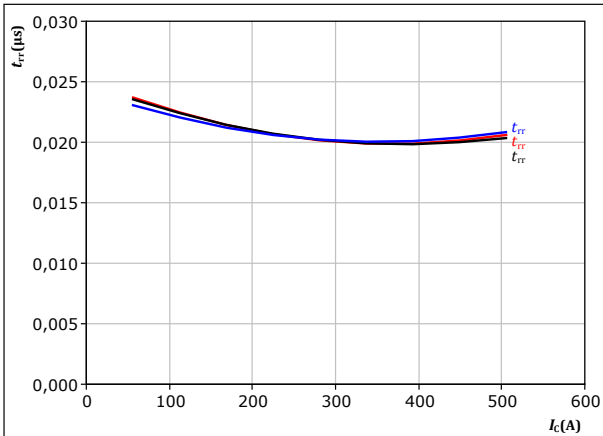
With an inductive load at

$T_j = 150$ °C
 $V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $I_c = 280$ A

figure 41.

FWD

Typical reverse recovery time as a function of collector current
 $t_{rr} = f(I_c)$



With an inductive load at

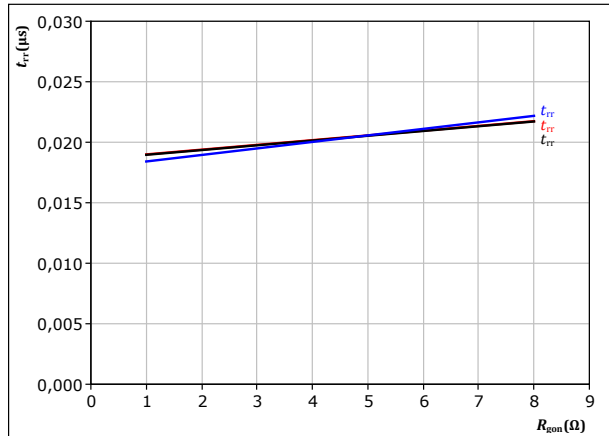
$V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $R_{gon} = 4$ Ω

T_j : 25 °C
125 °C
150 °C

figure 42.

FWD

Typical reverse recovery time as a function of IGBT turn on gate resistor
 $t_{rr} = f(R_{gon})$



With an inductive load at

$V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $I_c = 280$ A

T_j : 25 °C
125 °C
150 °C



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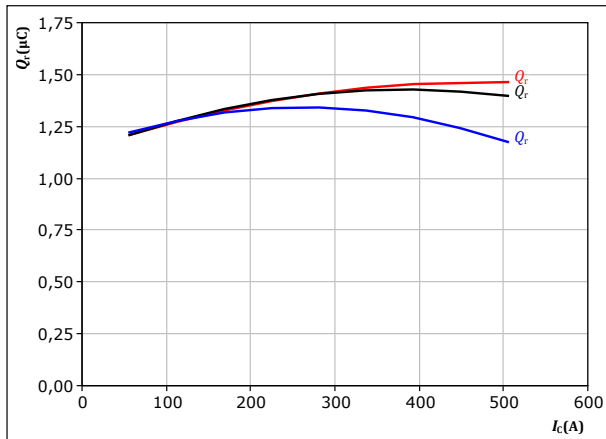
datasheet

Boost Switching Characteristics

figure 43. FWD

Typical recovered charge as a function of collector current

$$Q_r = f(I_c)$$



With an inductive load at

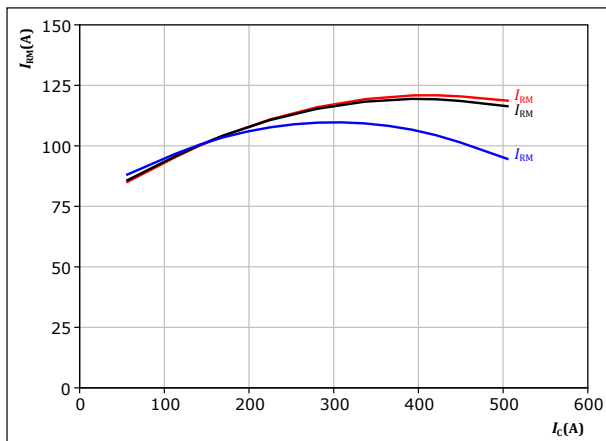
$V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $R_{gon} = 4$ Ω

T_j :
— 25 °C
— 125 °C
— 150 °C

figure 45. FWD

Typical peak reverse recovery current as a function of collector current

$$I_{RM} = f(I_c)$$



With an inductive load at

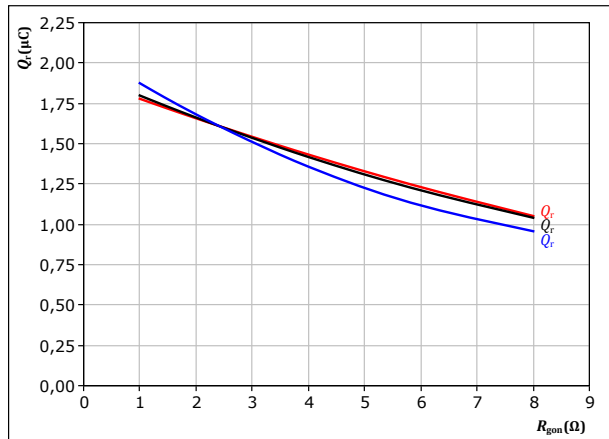
$V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $R_{gon} = 4$ Ω

T_j :
— 25 °C
— 125 °C
— 150 °C

figure 44. FWD

Typical recovered charge as a function of IGBT turn on gate resistor

$$Q_r = f(R_{gon})$$



With an inductive load at

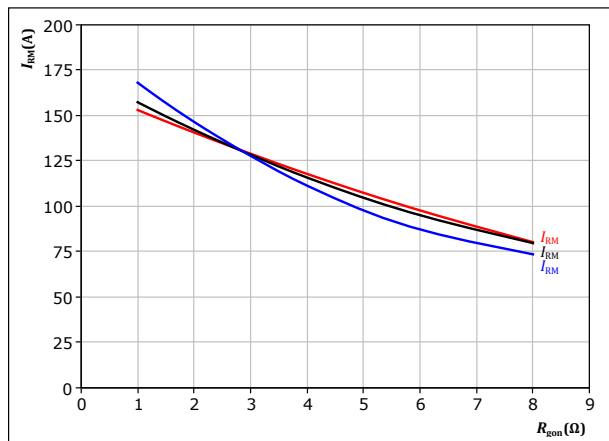
$V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $I_c = 280$ A

T_j :
— 25 °C
— 125 °C
— 150 °C

figure 46. FWD

Typical peak reverse recovery current as a function of IGBT turn on gate resistor

$$I_{RM} = f(R_{gon})$$



With an inductive load at

$V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $I_c = 280$ A

T_j :
— 25 °C
— 125 °C
— 150 °C

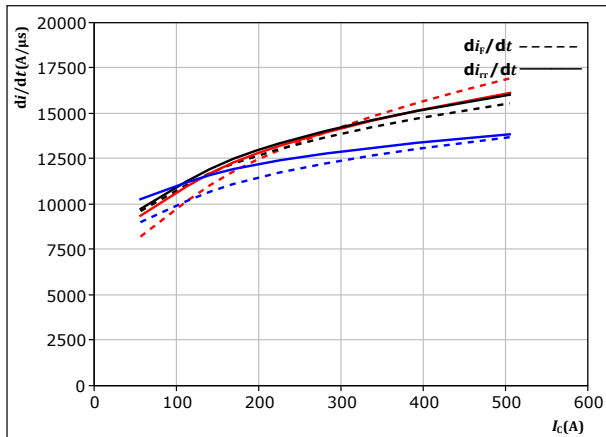


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Boost Switching Characteristics

figure 47. FWD

Typical rate of fall of forward and reverse recovery current as a function of collector current
 $di_f/dt, di_r/dt = f(I_C)$

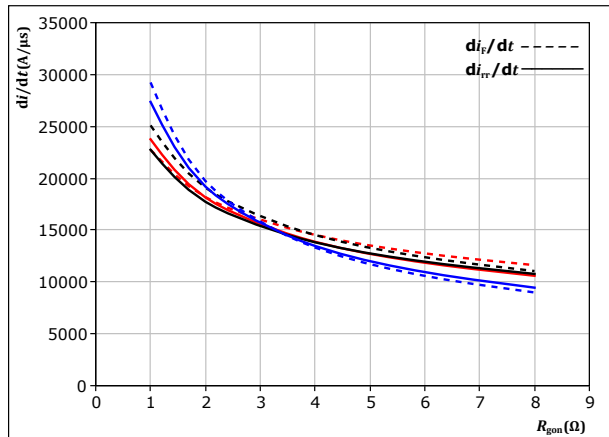


With an inductive load at

$V_{CE} = 600 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $R_{gon} = 4 \text{ } \Omega$
 $T_j = 25 \text{ } ^\circ\text{C}$
 $T_j = 125 \text{ } ^\circ\text{C}$
 $T_j = 150 \text{ } ^\circ\text{C}$

figure 48. FWD

Typical rate of fall of forward and reverse recovery current as a function of turn on gate resistor
 $di_f/dt, di_r/dt = f(R_{gon})$



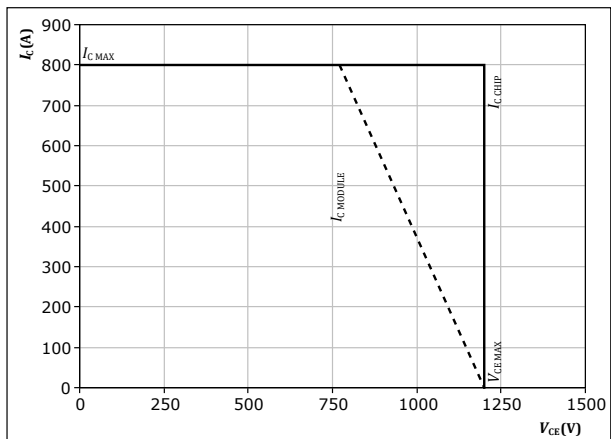
With an inductive load at

$V_{CE} = 600 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $I_C = 280 \text{ A}$
 $T_j = 25 \text{ } ^\circ\text{C}$
 $T_j = 125 \text{ } ^\circ\text{C}$
 $T_j = 150 \text{ } ^\circ\text{C}$

figure 49. IGBT

Reverse bias safe operating area

$I_C = f(V_{CE})$



At $T_j = 150 \text{ } ^\circ\text{C}$
 $R_{gon} = 4 \text{ } \Omega$
 $R_{goff} = 4 \text{ } \Omega$



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Switching Definitions

figure 50. IGBT

Turn-off Switching Waveforms & definition of t_{doff} , t_{Eoff} (t_{Eoff} = integrating time for E_{off})

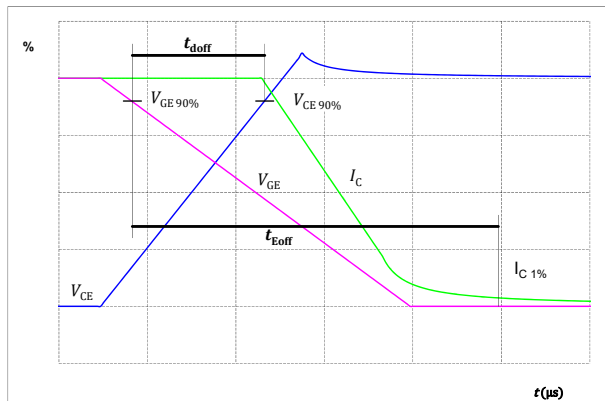


figure 51. IGBT

Turn-on Switching Waveforms & definition of t_{don} , t_{Eon} (t_{Eon} = integrating time for E_{on})

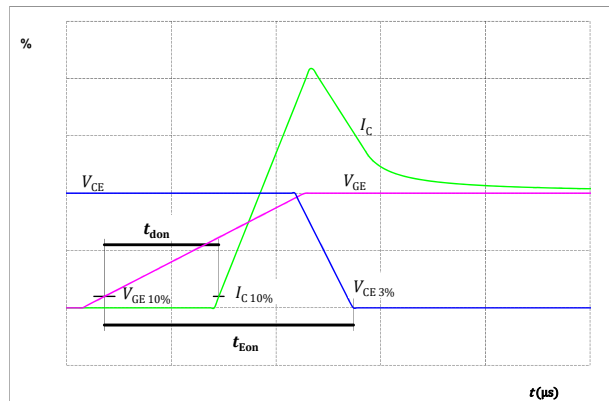


figure 52. IGBT

Turn-off Switching Waveforms & definition of t_f

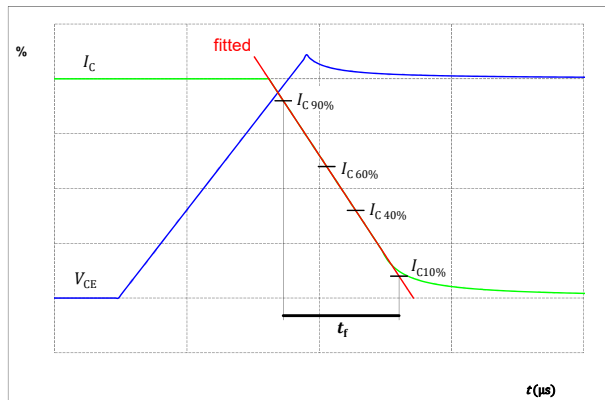
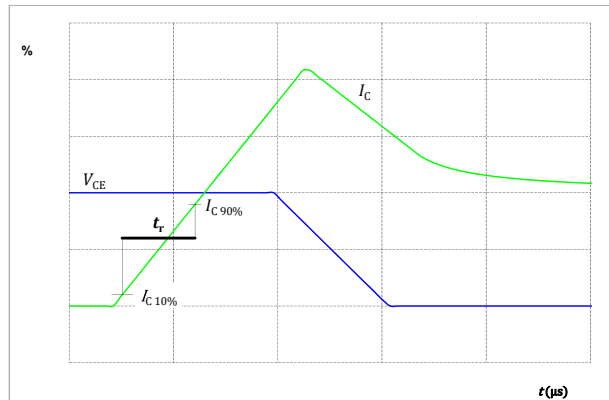


figure 53. IGBT

Turn-on Switching Waveforms & definition of t_r





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Switching Definitions

figure 54.

FWD

Turn-off Switching Waveforms & definition of t_{rr}

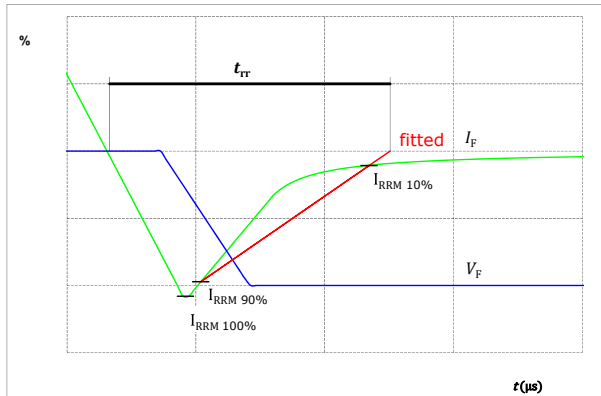
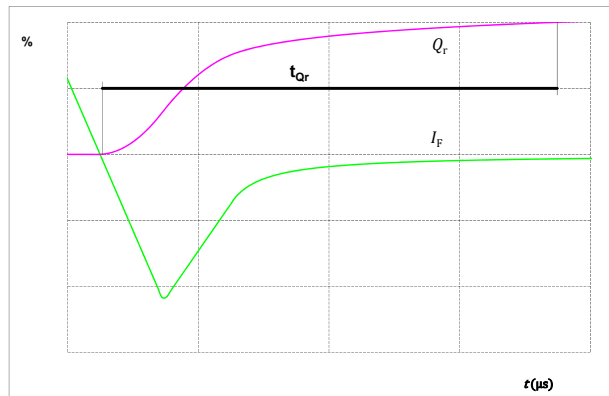


figure 55.

FWD

Turn-on Switching Waveforms & definition of t_{Qr} (t_{Qr} = integrating time for Q_r)





datasheet

Pin table [mm]							
Pin	X	Y	Function	33	46,56	22,4	S11-2
1	22,4	3,2	DC-1	34	49,76	22,4	S11-2
2	25,6	3,2	DC-1	35	19,2	6,4	G12-11
3	62,56	3,2	DC-2	36	28,8	6,4	G12-12
4	65,76	3,2	DC-2	37	22,4	6,4	S12-1
5	0	0	GND1	38	25,6	6,4	S12-1
6	16	0	GND1	39	59,36	6,4	G12-21
7	32	0	GND1	40	68,96	6,4	G12-22
8	40,16	0	GND2	41	62,56	6,4	S12-2
9	56,16	0	GND2	42	65,76	6,4	S12-2
10	72,16	0	GND2	43	19,2	25,6	G14-11
11	6,4	3,2	DC+1	44	28,8	25,6	G14-12
12	9,6	3,2	DC+1	45	22,4	25,6	S14-1
13	46,56	3,2	DC+2	46	25,6	25,6	S14-1
14	49,76	3,2	DC+2	47	59,36	25,6	G14-21
15	0	44,8	Ph1	48	68,96	25,6	G14-22
16	3,2	44,8	Ph1	49	62,56	25,6	S14-2
17	6,4	44,8	Ph1	50	65,76	25,6	S14-2
18	9,6	44,8	Ph1	51	3,2	41,6	G13-11
19	12,8	44,8	Ph1	52	12,8	41,6	G13-12
20	16	44,8	Ph1	53	6,4	41,6	S13-1
21	40,16	44,8	Ph2	54	9,6	41,6	S13-1
22	43,36	44,8	Ph2	55	43,36	41,6	G13-21
23	46,56	44,8	Ph2	56	52,96	41,6	G13-22
24	49,76	44,8	Ph2	57	46,56	41,6	S13-2
25	52,96	44,8	Ph2	58	49,76	41,6	S13-2
26	56,16	44,8	Ph2	59	65,76	44,8	Therm1
27	3,2	22,4	G11-11	60	72,16	44,8	Therm2
28	12,8	22,4	G11-12	61	0	22,4	P-1
29	6,4	22,4	S11-1	62	40,16	22,4	P-2
30	9,6	22,4	S11-1	63	32	25,6	N-1
31	43,36	22,4	G11-21	64	72,16	25,6	N-2
32	52,96	22,4	G11-22				

Outline

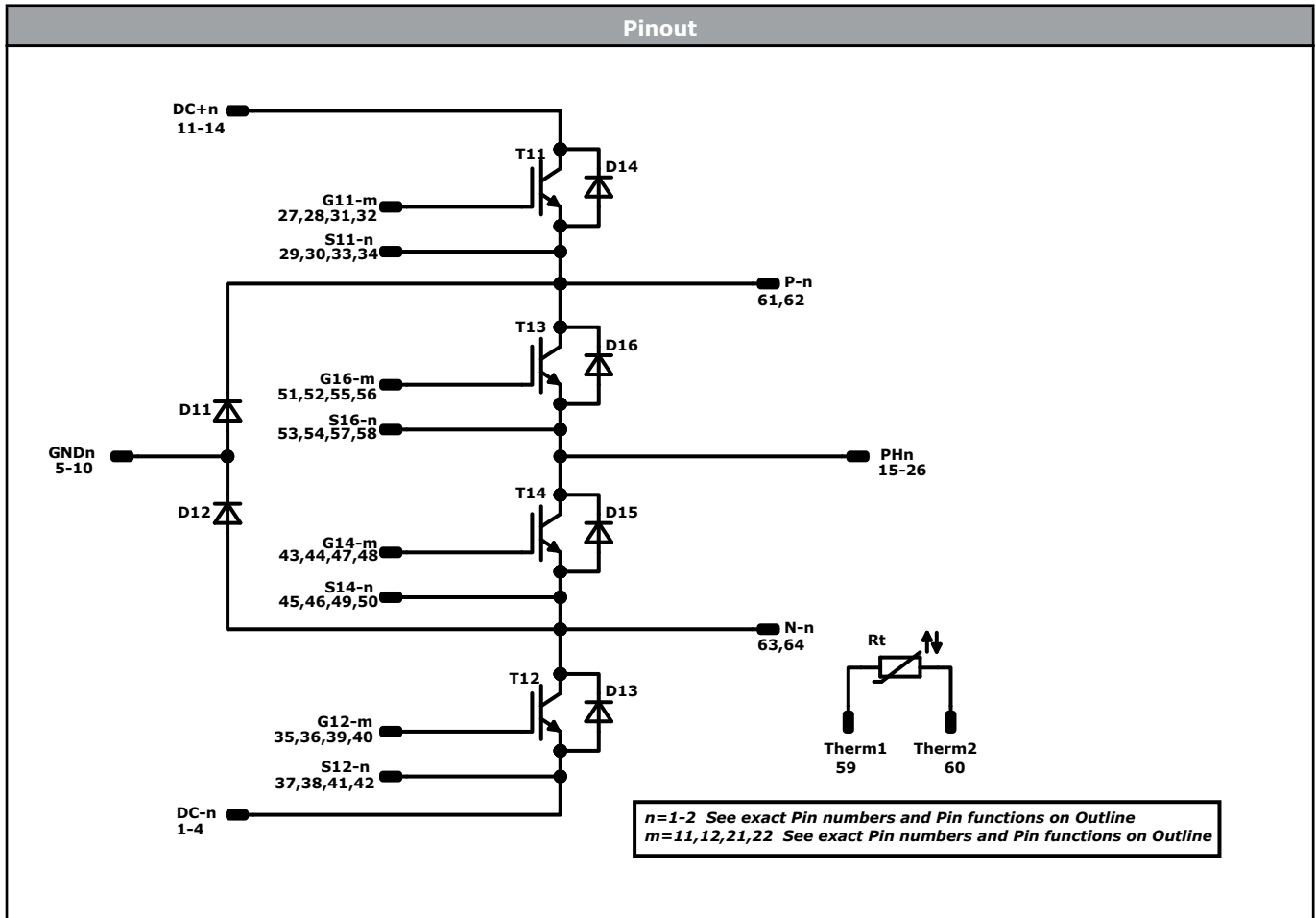
The technical drawing shows two views of the sensor module. The top view displays a rectangular PCB populated with numerous surface components, primarily concentrated along the edges. It features four mounting holes at the corners, each labeled 'ATA'. Dimension lines indicate a total width of 100 mm and a height of 47 mm. The bottom view shows the underside of the module, highlighting the pin headers and their arrangement. A note above the top view states: "Preliminary document only for samples!". A disclaimer at the bottom right reads: "Tolerance of proportions: ±0.05 mm at the end of pins. Deviation of coordinates also in any other without tolerance."



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datasheet



Identification					
ID	Component	Voltage	Current	Function	Comment
T11, T12	IGBT	1200 V	400 A	Buck Switch	Parallel devices with separate control. Values apply to complete device.
D11, D12	FWD	1200 V	140 A	Buck Diode	Parallel devices. Values apply to complete device.
T13, T14	IGBT	1200 V	400 A	Boost Switch	Parallel devices with separate control. Values apply to complete device.
D13, D14	FWD	1200 V	140 A	Boost Diode	Parallel devices. Values apply to complete device.
D15, D16	Rectifier	1600 V	168 A	Boost Sw. Inv. Diode	Parallel devices. Values apply to complete device.
Rt	Thermistor			Thermistor	



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datasheet

Packaging instruction				
Standard packaging quantity (SPQ) 24	>SPQ	Standard	<SPQ	Sample

Handling instruction
Handling instructions for <i>flow</i> E3BP packages see vincotech.com website.

Package data
Package data for <i>flow</i> E3BP packages see vincotech.com website.

Vincotech thermistor reference
See Vincotech thermistor reference table at vincotech.com website.

UL recognition and file number
Certification pending. For more information see vincotech.com website.

Document No.:	Date:	Modification:	Pages
30-E312NIA400H702-PM40F28-D1-14	15 Mar. 2025	Initial Release	

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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.